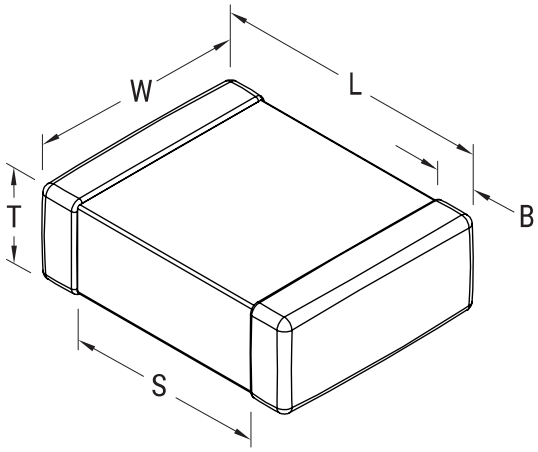
C0805X153J5GEC

ESD SMD Comm C0G, Ceramic, 0.015 uF, 5%, 50 VDC, C0G, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805, 0.6 mm



Click here for the 3D model.

General Information	
Series	ESD SMD Comm C0G
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	14 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0805
L	2mm +/-0.3mm
W	1.25mm +/-0.3mm
T	1.25mm +/-0.15mm
S	0.6mm MIN
B	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	Bulk, Bag
Packaging Quantity	1

Specifications	
Capacitance	0.015 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	50 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	66.6667 GOhms